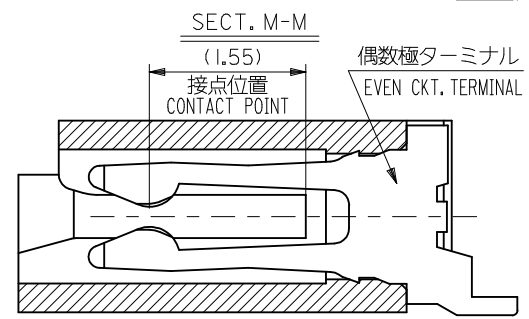
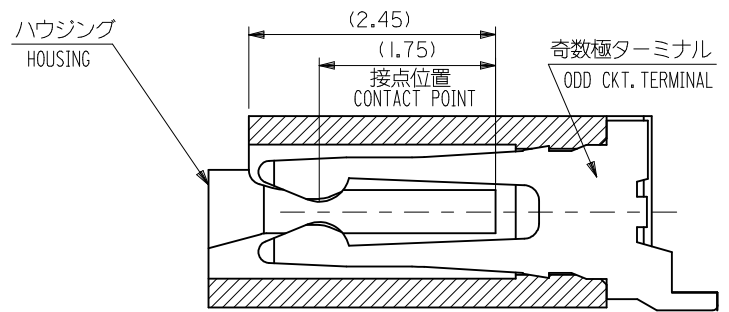
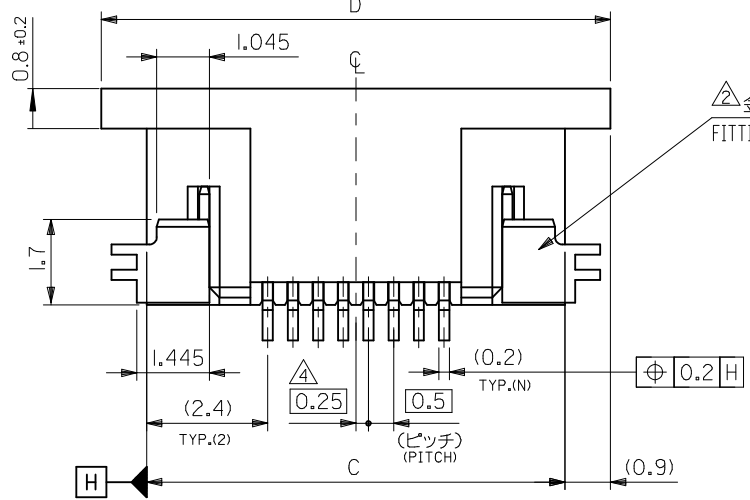
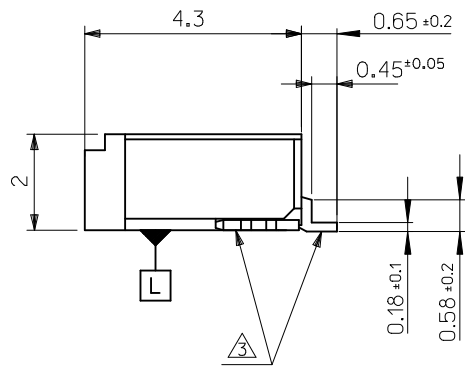
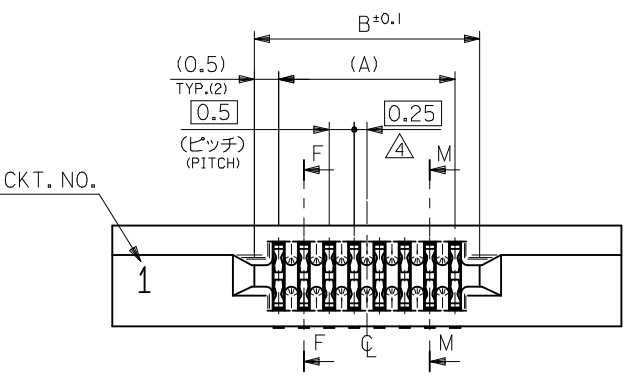
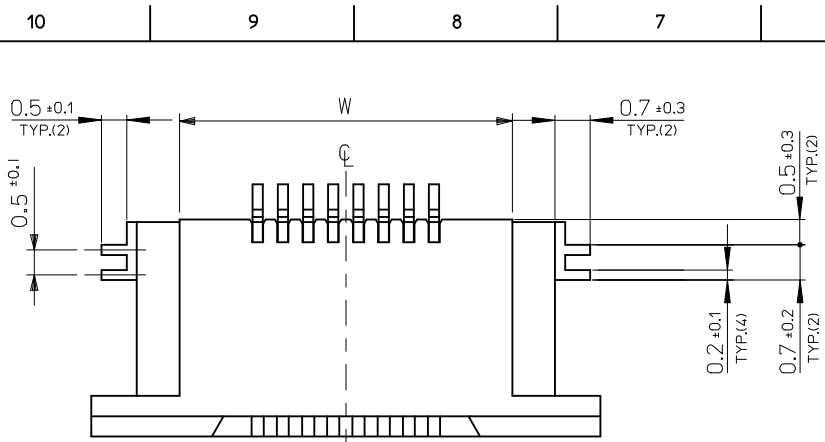


- 注記(NOTES)
1. 使用材料 (MATERIAL)
ターミナル (TERMINAL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫ビスマスマスメリ 1. 0マイクロメートル以上
TIN-BISMUTH 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
ハウジング (HOUSING): 46ナイロン (46NYLON), UL 94V-0
金具 (FITTING NAIL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫メッキ 1. 0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
 2. パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB, PATTERN.)
ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L に対し上方向 0.1MAX、下方向 0.15MAX、とする。
 3. MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L
UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.
偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
 5. 本製品は 52689-***40 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE 52689-***40.

MODEL NO. 52689-***49

REVISED EC NO: J2017-0300 DRWNGES CHKD: APPR:MSASAO	2016/12/01 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
				MM ONLY		---	METRIC	◎ □		
		0.25 UNDER	UNDER	±	DRAWN BY	DATE	TITLE			
		0.25 OVER	0.5 UNDER	±	H. KAWABATA	'04/02/03	0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-			
0.5 OVER	1.0 UNDER	±	CHECKED BY	DATE						
0 OVER	10 UNDER	±0.2	K. TOJO	'04/02/03	molex					
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE						
30 OVER		±0.3	M. SASAO	'04/02/03	SD-52689-034					
ANGULAR	±3 °		MATERIAL NO.	DOCUMENT NO.					SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						
			A3	SEE SHEET 2						



- 注記(NOTES)
1. 使用材料 (MATERIAL)
ターミナル (TERMINAL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫ビスマスマスメリ 1. 0マイクロメートル以上
TIN-BISMUTH 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
ハウジング (HOUSING): 46ナイロン (46NYLON), UL 94V-0
金具 (FITTING NAIL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫メッキ 1. 0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
 2. パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB. PATTERN.)
ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L に対し上方向 0.1MAX. 下方向 0.15MAX. とする。
 3. MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L
UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.
偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
 5. 本製品は 52689-***40 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE 52689-***40.

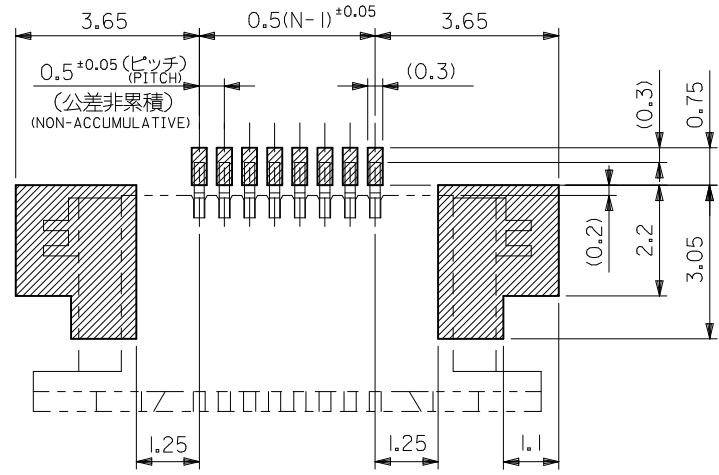
MODEL NO. 52689-***49
DESIGN UNITS METRIC
THIRD ANGLE PROJECTION

0.5 FPC CONN NON ZIF
HSG ASSY FOR SMT(R/A)
-LEAD FREE-

molex

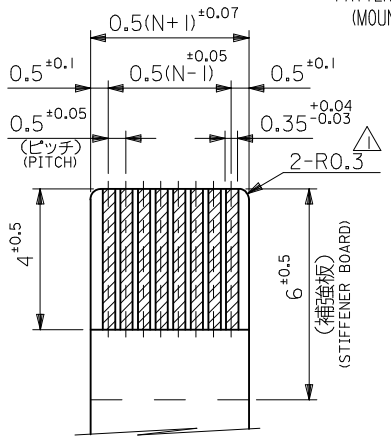
DOCUMENT NO. SD-52689-034
SHEET NO. 1 OF 2

GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC
0.25 UNDER	UNDER	±	DRAWN BY	DATE	TITLE	
0.25 OVER	0.5 UNDER	±	H. KAWABATA	'04/02/03	0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-	
0.5 OVER	1.0 UNDER	±	CHECKED BY	DATE		
0 OVER	10 UNDER	±0.2	K. TOJO	'04/02/03		
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE		
30 OVER		±0.3	M. SASAO	'04/02/03		
ANGULAR	±3 °		MATERIAL NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE SHEET 2			
			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

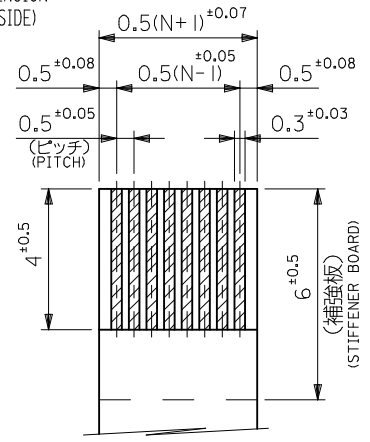


参考基板レイアウト
(マウント面)

REFERENCE P.C. BOARD
PATTERN DIMENSION
(MOUNTING SIDE)



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

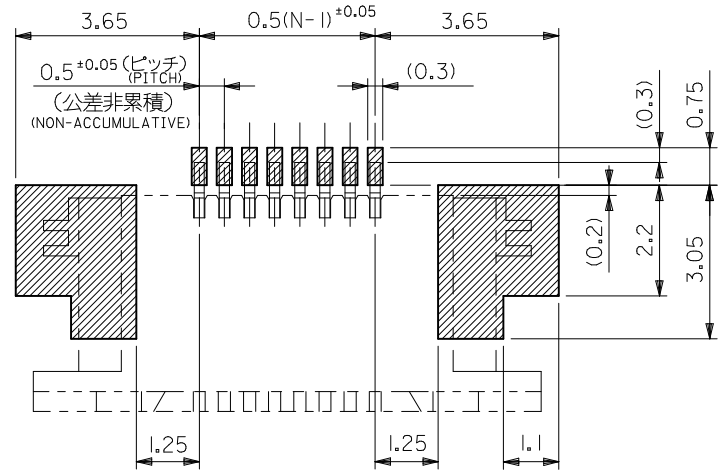
ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

△ R0.3は、FPCの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

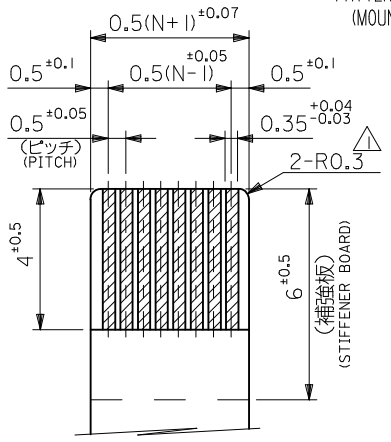
52689-***49	17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
MODEL NO.	13.6	17.1	15.3	11.5	10.5	52689-2287	52689-2249	22
	W	D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	極数 CKT.
						ORDER No. オーダー番号		

REVISED EC NO: J2017-0300 DRAWINGS CHKD: APPR: MSASAO	DESCRIPTION 2016/12/01 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		0.25 UNDER UNDER ±	0.25 OVER 0.5 UNDER ±	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-			
		0.5 OVER 1.0 UNDER ±	0 OVER 10 UNDER ±0.2	CHECKED BY K. TOJO	DATE '04/02/03				
		10 OVER 30 UNDER ±0.25	30 OVER ±0.3	APPROVED BY M. SASAO	DATE '04/02/03				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

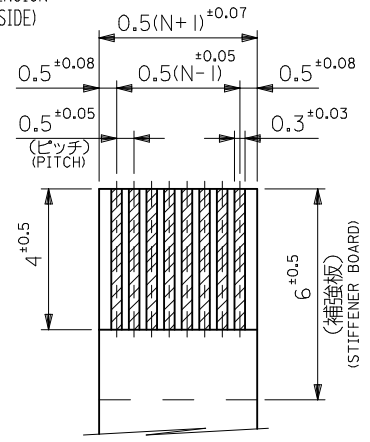


参考基板レイアウト
(マウント面)

REFERENCE P.C. BOARD
PATTERN DIMENSION
(MOUNTING SIDE)



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
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BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

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52689-***49	17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
MODEL NO.	13.6	17.1	15.3	11.5	10.5	52689-2287	52689-2249	22
	W	D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	極数 CKT.
						ORDER No. オーダー番号		

REVISED EC NO: J2017-0300 DRAWINGS CHKD: APPR: MSASAO	DESCRIPTION 2016/12/01 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		0.25 UNDER UNDER ±	0.25 OVER 0.5 UNDER ±	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-			
		0.5 OVER 1.0 UNDER ±	0 OVER 10 UNDER ±0.2	CHECKED BY K. TOJO	DATE '04/02/03				
		10 OVER 30 UNDER ±0.25	30 OVER ±0.3	APPROVED BY M. SASAO	DATE '04/02/03				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				